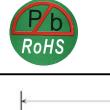
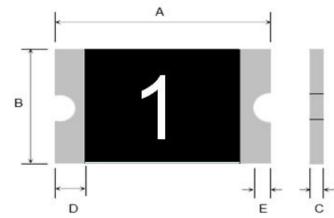
# JK-SMD0603-005 PPTC DEVICES Part Number: Q/JKTD-15-005





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Terminal pad materials :Tin-Plated Nickle-copper

Terminal pad solderability : Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.

Marking : Part identification 1=005

Model	Marking	А		В		С		D	Е
Widdel	Marking	Min.	Max.	Min.	Max.	Min.	Max	Min.	Max.
JK-SMD0603-005	1	1.45	1.85	0.65	1.05	0.40	1.00	0.15	0.40

#### Table2 :PERFORMANCE RATINGS:

Madal	Marking	V <sub>max</sub>	I <sub>max</sub>	Ihold	I <sub>trip</sub>	P <sub>d</sub>	Maxin Time To		Resi	stance
Model	Marking	(Vdc)	(A)	@25°C (A)	@25°C (A)	TypTime(W)CurrentTimeR1minR	$R1_{max}$			
				(A)	(A)	(W)	(A)	(Sec)	$(\Omega)$	$(\Omega)$
JK-SMD0603-005	1	15.0	20	0.05	0.15	0.50	0.2	1.00	3.0	35.000

#### Table3:Test Conditons and Standards

Item	Test Conditon	Standard		
Initial Resistance	25°C	3.00~35.000Ω		
I <sub>H</sub>	25°C, 0.05A, 60min	No Trip		
Ttrip	25°C, 0.2A	≤1.0S		
Trip endurance	15V, 20A, 60min	No arcing or burning		

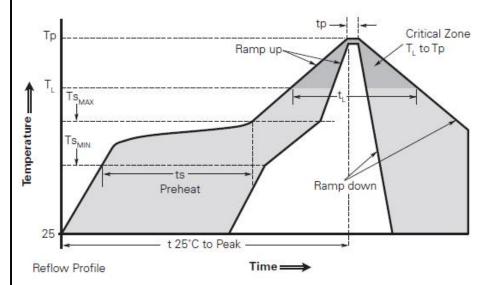
Operating Temperature: -40°C TO 85°C Packaging: Bulk ,5000pcs per bag

SHENZHEN JINRUI ELECTRONIC MATERIAL CO.,LTD6 F DISTRICT NO. 3000046 BLDG Hi-Tech SCIENCE &INDUSTRY PARKSHANGKENG COMMUNITY GUANLAN STREET BAOAN SHENZHENTEL:0755-2654632726584158Web Site:www.jkpptc.comE-mail:customer@jkpptc.com

## JK-SMD0603-005 PPTC DEVICES Part Number: Q/JKTD-15-005



#### Solder reflow conditions



Profile Feature	Pb-Free Assembly			
Average ramp up rate (Ts <sub>MAX</sub> to Tp)	3°C/second max.			
Preheat				
<ul> <li>Temperature min. (Ts<sub>MIN</sub>)</li> </ul>	150°C			
<ul> <li>Temperature max. (Ts<sub>MAX</sub>)</li> </ul>	200°C			
<ul> <li>Time (ts<sub>MIN</sub> to ts<sub>MAX</sub>)</li> </ul>	60-120 seconds			
Time maintained above:				
• Temperature (T <sub>L</sub> )	217°C			
• Time (t <sub>L</sub> )	60-150 seconds			
Peak/Classification temperature (Tp)	260°C			
Time within 5°C of actual peak temperat	ure			
Time (tp)	30 seconds max.			
Ramp down rate	3°C/second max.			
Time 25°C to peak temperature	8 minutes max.			

• Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.

• Devices are not designed to be wave soldered to the bottom side of the board.

• Recommended maximum paste thickness is 0.25mm (0.010inch).

• Devices can be cleaned using standard industry methods and solvents.

• Soldering temprature profile meets RoHs leadfree process.

Note: All temperatures refer to topside of the package, measured on the package body surface.

Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

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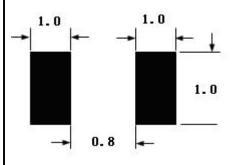
## JK-SMD0603-005 PPTC DEVICES Part Number: Q/JKTD-15-005



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## Recommended pad layout (mm)



### WARNING

 $\cdot$  Use PPTC beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.

• PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

• Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic components.

· Use PPTC with a large inductance in circuit will generate a circuit voltage (L di/dt) above the rated voltage of the PPTC.

· Avoid impact PPTC device its thermal expansion like placed under pressure or installed in limited space.

 $\cdot$  Contamination of the PPTC material with certain silicon based oils or some aggressive solvents can adversely impact the performance of the devices.PPTC SMD can be cleaned by standard methods.

 $\cdot$  Requests that customers comply with our recommended solder pad layouts and recommended reflow profile. Improper board layouts or reflow profilecould negatively impact solderability performance of our devices.

# SHENZHEN JINRUI ELECTRONIC MATERIAL CO.,LTD6 F DISTRICT NO. 3000046 BLDG Hi-Tech SCIENCE &INDUSTRY PARKSHANGKENG COMMUNITY GUANLAN STREET BAOAN SHENZHEN